



HPN2907A

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HPN2907A is designed for general purpose amplifier and high speed, medium-power switching applications.

Features

- Low Collector Saturation voltage
- High Speed Switching
- For Complementary Use with NPN Type HPN2222A

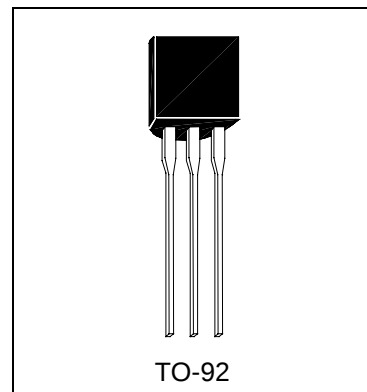
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C)..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage..... -60 V
VCEO Collector to Emitter Voltage -60 V
VEBO Emitter to Base Voltage..... -5 V
IC Collector Current -600 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-10uA, IE=0
BVCEO	-60	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IC=-10uA, IC=0
ICBO	-	-	-10	nA	VCB=-50V, IC=0
ICEX	-	-	-50	nA	VCE=-30V, VBE=-0.5V
*VCE(sat)1	-	-0.2	-0.4	V	IC=-150mA, IB=-15mA
*VCE(sat)2	-	-0.5	-1.6	V	IC=-500mA, IB=-50mA
*VBE(sat)1	-	-	-1.3	V	IC=-150mA, IB=-15mA
*VBE(sat)2	-	-	-2.6	V	IC=-500mA, IB=-50mA
*hFE1	75	-	-		VCE=-10V, IC=-100uA
*hFE2	100	-	-		VCE=-10V, IC=-1mA
*hFE3	100	-	-		VCE=-10V, IC=-10mA
*hFE4	100	180	300		VCE=-10V, IC=-150mA
*hFE5	50	-	-		VCE=-10V, IC=-500mA
fT	200	-	-	MHz	VCE=-20V, IC=-50mA, f=100MHz
Cob	-	-	8	pF	VCB=-10V, f=1MHz

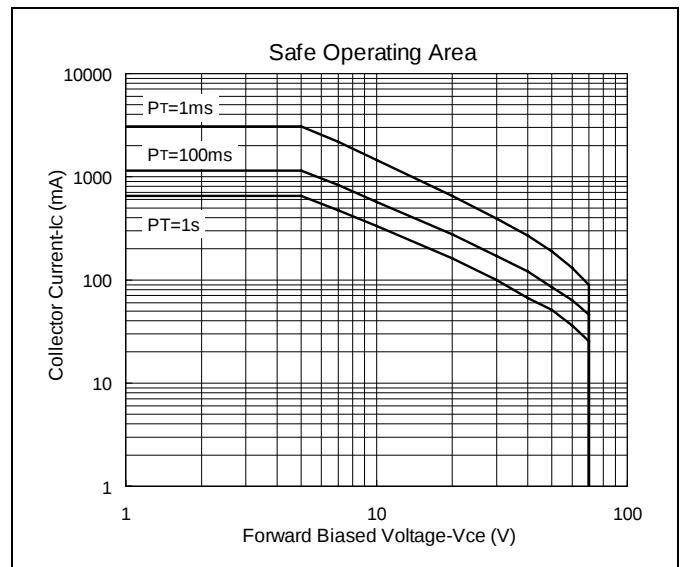
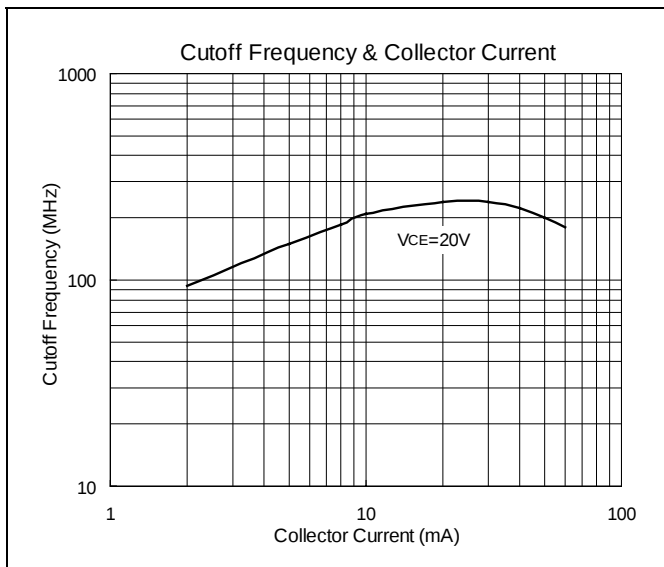
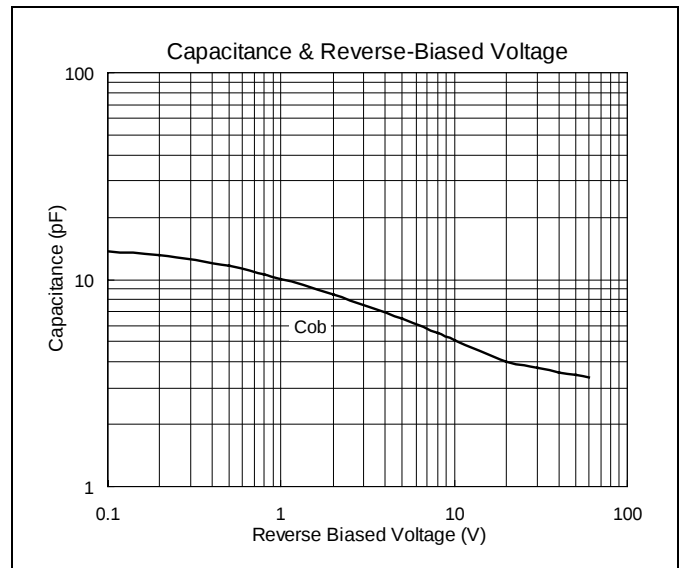
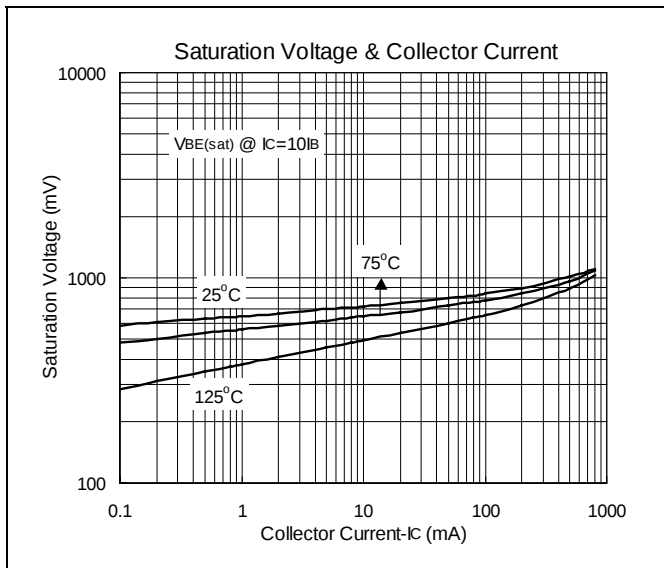
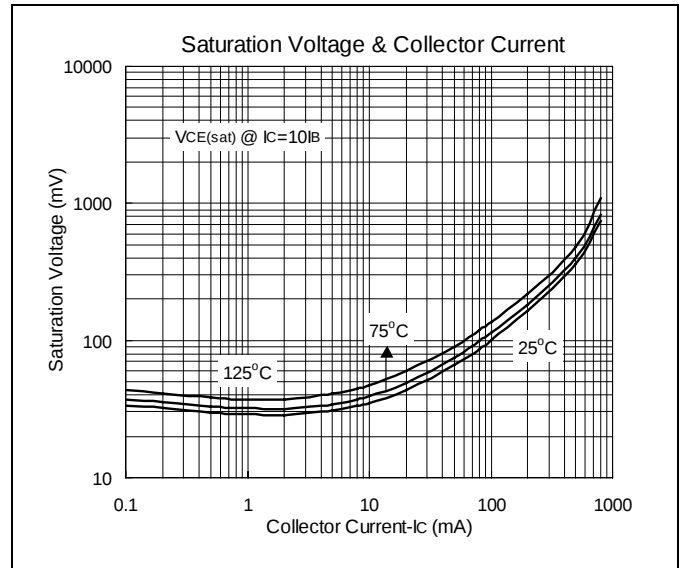
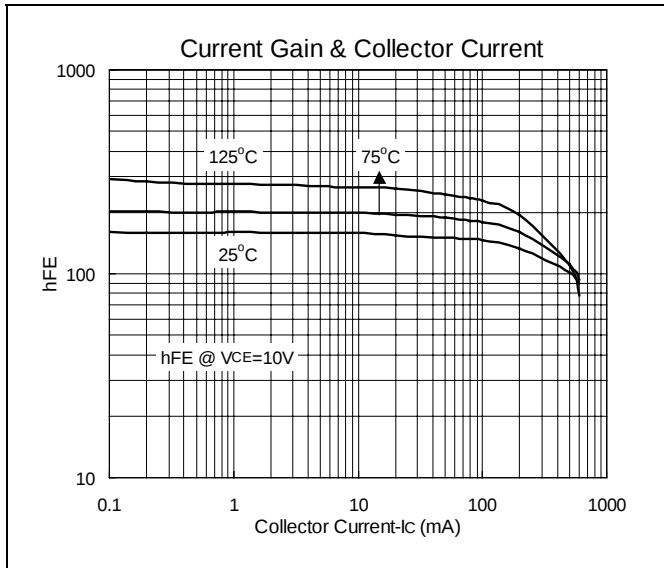
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

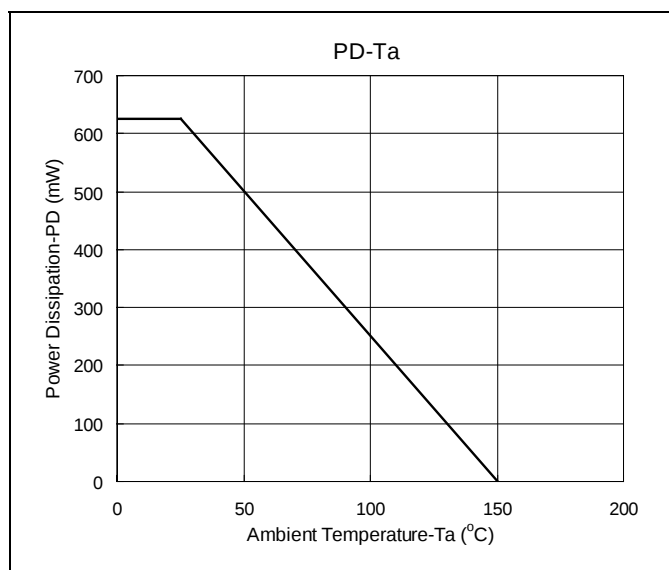


TO-92



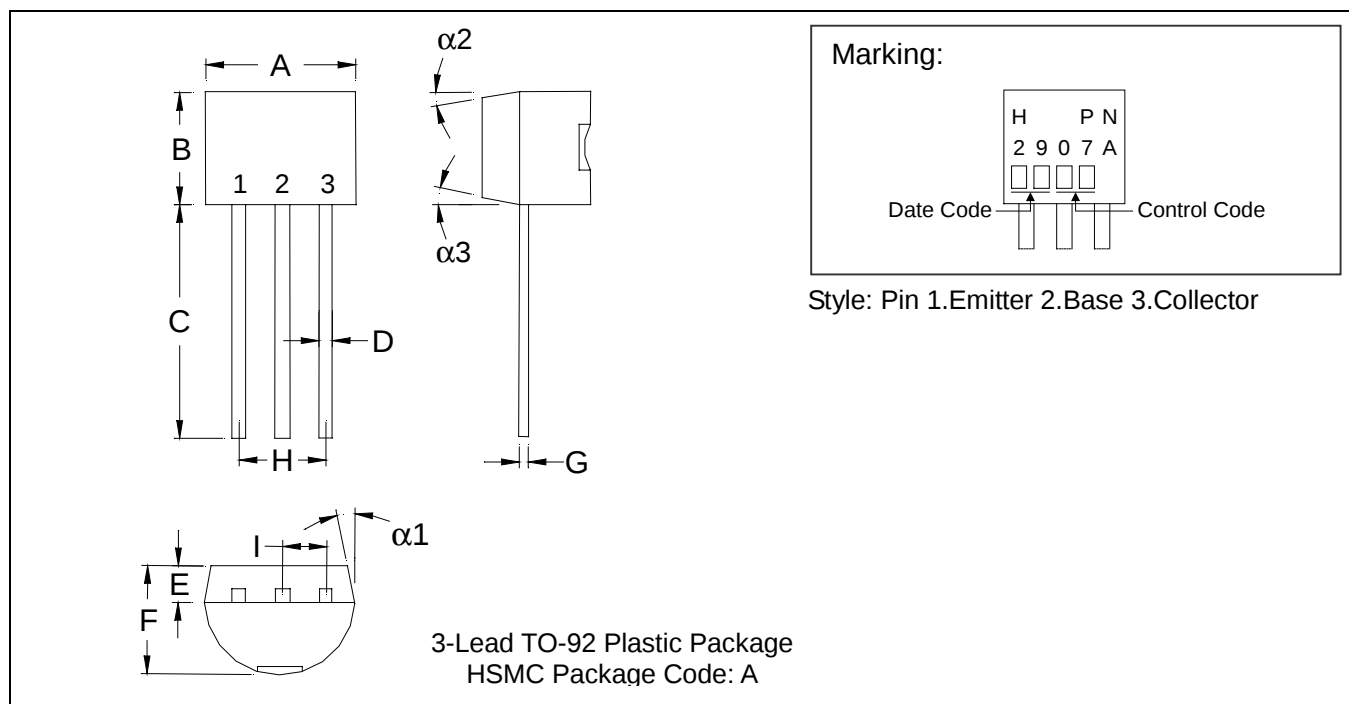
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes: 1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.
2. Controlling dimension: millimeters.
3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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